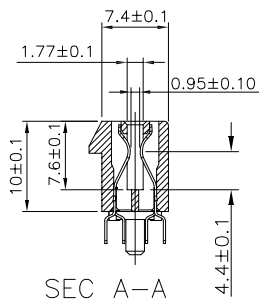
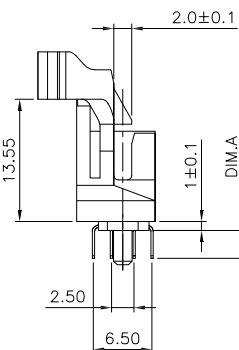
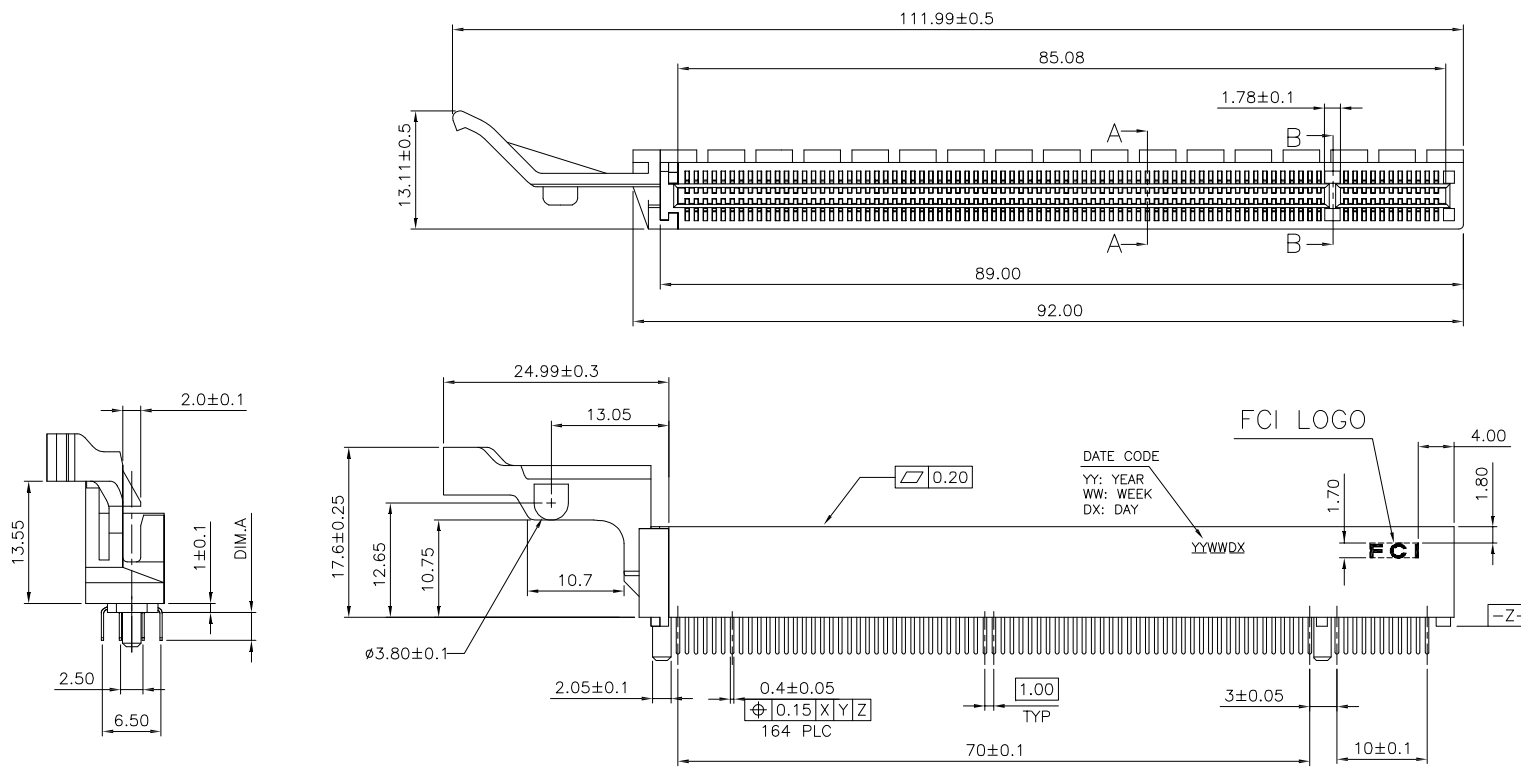


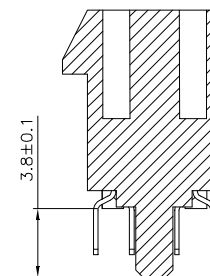


A



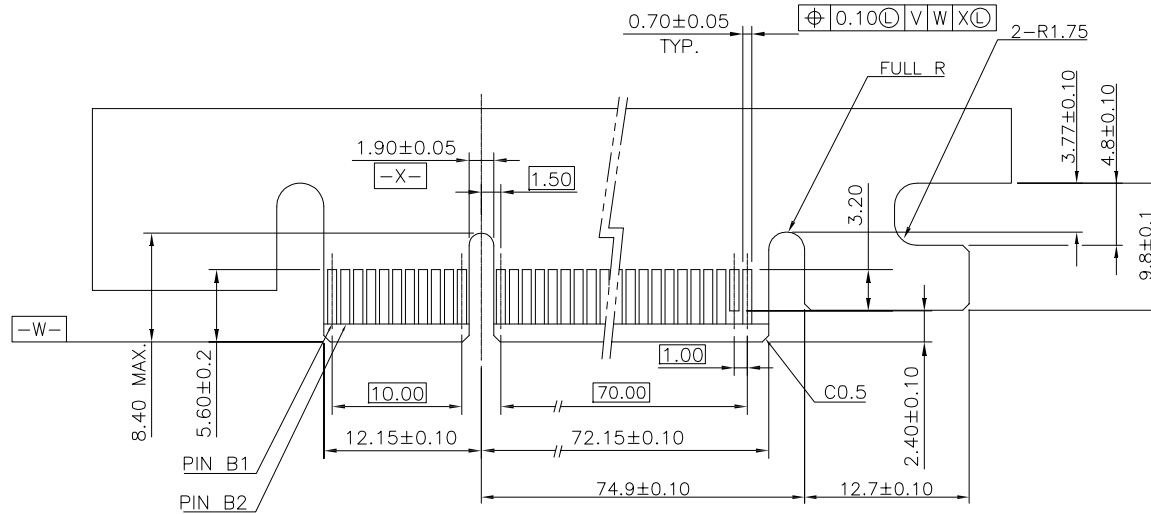
SEC A-A

PART NUMBER	DIM.A
10083987-XXX13TLF	3.10±0.15
10083987-XXX23TLF	2.30±0.15

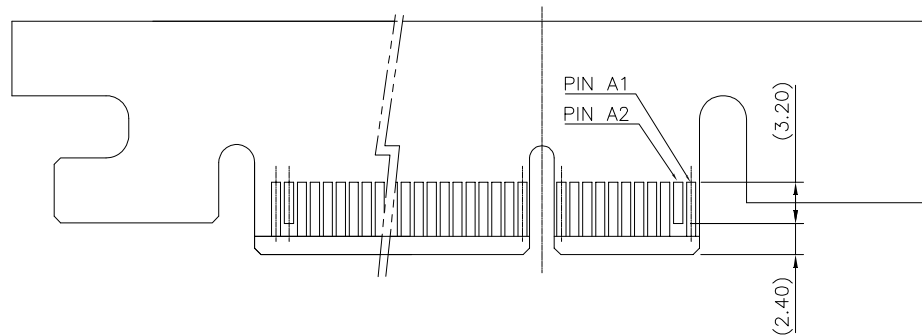
SEC B-B
SECALE 2:1

B

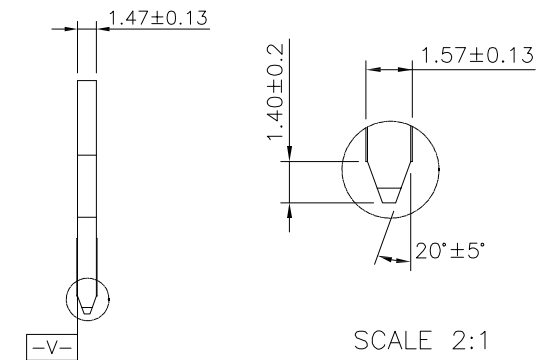
mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		 www.fciconnect.com			
ltr	ecn no	dr	date	linear	.X ± 0.38			projection 	title PCI-E INTEGRATED TYPE GEN3 CARD EDGE ASS'Y 			
A	T07-1180	J.H	12/27/07		.XX ± 0.25							
B	T10-0030	J.H	1/03/10		.XXX ± 0.10							
C	ELX-DG-21161-1	ST	05/27/16	angles	0° ± 2°							
				dr	STONE LI	05/27/15		product family			EDGE CARD	code
				enrg	STONE LI	05/27/15		size			dwg no	TWN
				chr	/	/		scale				sheet
				appd	PM ZHENG	05/27/15	1:1	A4			10083987	1 of
sheet	revision	C	C	C								
index	sheet	1	2	3								



← I/O PANEL DIRECTION
PRIMARY (COMPONENT) SIDE

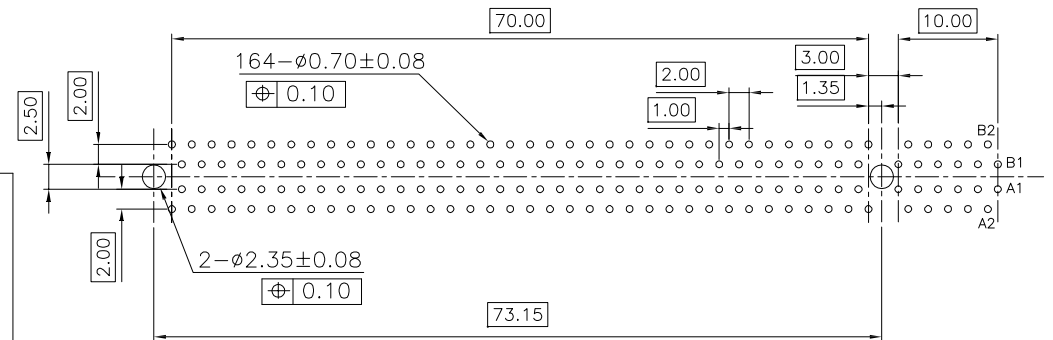


I/O PANEL DIRECTION →
SECONDARY (SOLDER) SIDE



SCALE 2:1

ADD-IN CARD EDGE-FINGER DIMENSIONS



RECOMMENDED FOOTPRINT LAYOUT

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		FCI		
ltr	ecn no	dr	date	linear	.X ± 0.38		projection		www.fciconnect.com		
					.XX ± 0.25				title PCI-E INTEGRATED TYPE GEN3 CARD EDGE ASS'Y		
				angles	.XXX ± 0.10						
					0° ± 2°						
				dr	STONE LI	05/27/15	MM		product family		code
				enr	STONF LI	05/27/15			EDGE CARD		TWN
				chr	/	/	scale		size dwg no		sheet
				appd	PM ZHENG	05/27/15	1:1		A4		2 of
sheet index	revision sheet								cage code		
									22526		

NOTES:

1.MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
LATCHS: THERMOPLASTIC WITHOUT GLASS FIBER, UL94-HB (PA66).
CONTACTS: COPPER ALLOY.

2.FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,
60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50u" MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER
BY 25 DEGREE.

4. DURABILITY: 50 CYCLES.

5. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

- a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 1.5um min. MATTE PURE TIN OVER 1.27um MIN.
NICKEL UNDERPLATE.
- b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C $\pm$ 5C^o
SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH
A 1.57MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10083987 -x x x x x x LF

HOUSING COLOR OPTIONS

1-BLACK FOR BASE & RM
4-BLUE (297C) FOR BASE & RM

APPLICATIONS

LF- LEAD FREE FOR PLATING OPTIONS 0,1,2

PACKAGING OPTIONS

T-TRAY PACKAGING

PEGS OPTIONS

1-PLASTIC POST

POS OPTIONS

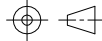
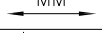
3-164

TERMINAL PLATING OPTIONS

0-50u" Ni UNDERPLATE
30u" Au CONTACT AREA
100u" TIN TAIL AREA
1-50u" Ni UNDERPLATE
15u" Au CONTACT AREA
100u" TIN TAIL AREA
2-50u" Ni UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA

TAIL LENGTH OPTION (DIM.A)

1- 3.10MM
2- 2.30MM

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com			
ltr	ecn no	dr	date	linear	.X $\pm$ 0.38		title PCI-E INTEGRATED TYPE GEN3 CARD EDGE ASS'Y 			
					.XX $\pm$ 0.25					
					.XXX $\pm$ 0.10					
				angles	0 ^o $\pm$ 2 ^o	 MM  1:1	product family		EDGE CARD	
				dr	STONE LI	05/27/15	size		dwg no	
				enrg	STONF LI	05/27/15	A4		10083987	
				chr	/	/	code		TWN	
				appd	PM ZHENG	05/27/15	sheet		3 of	
sheet	revision									
index	sheet									